**AiT Semiconductor Inc.** 

-40V, -45A P-CHANNEL ENHANCEMENT MODE POWER MOSFET

### DESCRIPTION

The AM45P04D is available in TO-252 Package.

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VDSS	RDSON	ID
-40V	8.9 mΩ	-45A

### APPLICATIONS

- Load Switch
- **PWM Application**
- **Power Management**

### **ORDERING INFORMATION**

Package Type	Part Number		
TO-252	D	AM45P04DVR	
SPQ: 2,500pcs/Reel	D	AIVI43P04DVR	
Note	R: Tape & Reel		
nole	V: Halogen free Package		
AiT provides all RoHS products			

### **ABSOLUTE MAXIMUM RATINGS**

$T_J$ = 25°C, unless otherwise specified.		
V <sub>DS</sub> , Drain-to-Source Voltage		-40V
V <sub>GS</sub> , Gate-to-Source Voltage		±20V
I <sub>D</sub> , Continuous Drain Current	T <sub>C</sub> = 25°C	-45A
	T <sub>C</sub> = 100°C	-27A
I <sub>DM</sub> , Pulsed Drain Current <sup>(1)</sup>		-180A
E <sub>AS</sub> , Single Pulse Avalanche Energy <sup>(2)</sup>		100mJ
P <sub>D</sub> , Power Dissipation	T <sub>c</sub> = 25°C	40W
Rejc, Thermal Resistance, Junction to	3.1°C/W	
T <sub>STG</sub> , Storage Temperature Range		-55℃ ~ +150℃
T <sub>J</sub> , Junction Temperature Range		-55°C ~ +150°C

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

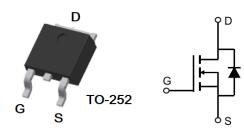
(1) Repetitive Rating: pulse width limited by maximum junction temperature.

(2)  $E_{AS}$  condition: Starting TJ=25°C, VDD=20V, VG=10V, RG=250hm, L=0.5mH, IAS=17A

# FEATURE

- -40V, -45A
- $R_{DS(ON)}$  Typ. = 8.9m $\Omega$  @ V<sub>GS</sub> = -10V
- R<sub>DS(ON)</sub> Typ. =12.8mΩ @ V<sub>GS</sub> = -4.5V
- Advanced Trench Technology
- Excellent RDS(ON) and Low Gate Charge

### **PIN DESCRIPTION**



**TO-252** 

Pin #	Symbol	Function
1	G	Gate
2,4	D	Drain
3	S	Source



MOSFET -40V, -45A P-CHANNEL ENHANCEMENT MODE POWER MOSFET

# ELECTRICAL CHARACTERISTICS

#### $T_J$ = 25°C, unless otherwise specified.

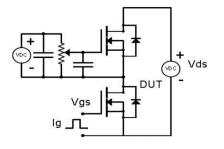
Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	V(BR)DSS	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250µA	-40	-	-	V
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = -40V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	lgss	$V_{GS}$ = ±20V, $V_{DS}$ =0V	-	-	±100	nA
On Characteristics			-			•
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{DS}$ = $V_{GS}$ , $I_D$ = -250 $\mu$ A	-1.1	-1.5	-2.2	V
		$V_{GS}$ = -10V, $I_D$ = -15A	-	8.9	11.6	mΩ
Static Drain-Source ON-Resistance *	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A	-	12.8	16.6	
Dynamic Characteristics	1			I		
Input Capacitance	Ciss		-	1997	-	pF
Output Capacitance	Coss	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V, f=1.0MHZ	-	258	-	
Reverse Transfer Capacitance	Crss		-	205	-	
Total Gate Charge	Qg	- V <sub>DS</sub> = -20V , I <sub>D</sub> =-11V - V <sub>GS</sub> =0V ~ -10V	-	35	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	6.2	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	7.3	-	
Switching Characteristics	1	1		1		
Turn-On Delay Time	t <sub>d(on)</sub>		-	10	-	ns
Turn-On Rise Time	tr	$V_{DD}$ = -20V, $I_D$ = -11A	-	20	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_{GEN}=2.5\Omega$ ,	-	51	-	
Turn-Off Fall Time	t <sub>f</sub>	- V <sub>GS</sub> = -10V,	-	28	-	
Reverse Diode	1			L		
Maximum Continuous Drain to		ls -	-	-	-45	А
Source Diode Forward Current	Is					
Maximum Pulsed Drain to Source					100	_
Diode Forward Current	I <sub>SM</sub>	-	-	-	-180	A
Drain to Source Diode Forward		V <sub>SD</sub> I <sub>S</sub> = -11A, V <sub>GS</sub> =0V	-	-	1.2	V
Voltage	VSD					
Body Diode Reverse Recovery Time	trr		-	35	-	ns
Body Diode Reverse Recovery		$I_{\rm F} = -11A$		40		
Charge	Q <sub>rr</sub> di/dt = 100A/us		-	40	-	nC

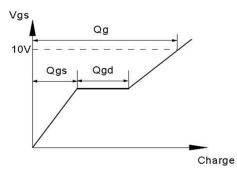
\* Pulse test: Pulse width  $\leq$  300µs, Duty Cycle  $\leq$  2%.



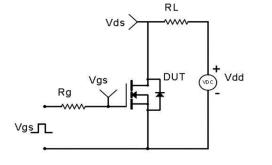
# TEST CIRCUIT

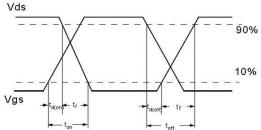
Fig 1. Gate Charge Test Circuit & Waveform



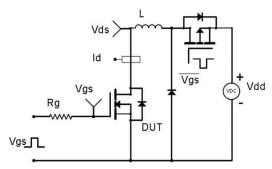


### Fig 2. Resistive Switching Test Circuit & Waveforms





### Fig 3. Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



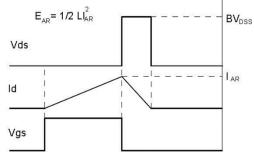
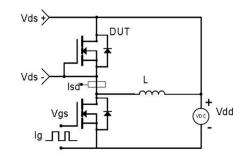
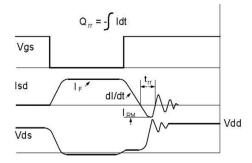


Fig 4. Diode Recovery Test Circuit & Waveforms

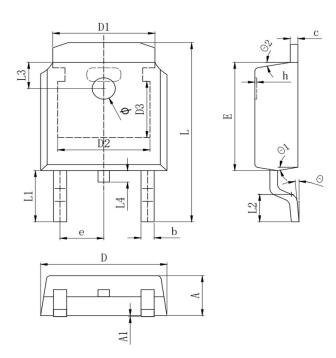






# PACKAGE INFORMATION

Dimension in TO-252 (Unit: mm)



Or much all	Millimeters			
Symbol	Min.	Max.		
A	2.200	2.400		
A1	0.000	0.127		
b	0.640	0.740		
С	0.460	0.580		
D	6.500	6.700		
D1	5.334 REF.			
D2	4.826 REF.			
D3	3.166 REF.			
E	6.000	6.200		
е	2.286 REF.			
h	0.000	0.200		
L	9.900	10.300		
L1	2.888 REF.			
L2	1.400	1.700		
L3	1.600 REF.			
L4	0.600	1.000		
Φ	1.100	1.300		
θ	0°	8°		
θ1	9° TYP.			
θ2	9° TYP.			



### **IMPORTANT NOTICE**

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